





UPB345A

3300-3600MHz UPB Series TDD Bandpass Filter

Features

- Low Loss with High Rejection
- Low ripple
- Universal footprint across family for all TDD bands

Applications

- Wireless Infrastructure applications
- High-performance carrier-grade single-band TDD Pico-cell basestations for up to 1.0W at the antenna port.

Part Dimensions: 9.0×6.7 est $\times 3.1$ mm • <1.0 est g Materials: Ag plated ceramic block with tin plated brass shield

Description

Surface mount ceramic bandpass filter supports a universal footprint across all TDD frequency bands enabling the use of a common system PCB. Superior rejection, insertion loss, reliability, as well as both peak and average power handling compared other bandpass filter technologies.

Electrical Specifications

Parameter	Frequency (MHz)	Typical at 25°C	Spec. at 25°C	Spec. over -40°C to +85°C
Nominal Impedance	-	50 ohms	-	-
Average Input Power	-	-	-	2.0 Watt max
Peak Input Power	-	-	-	20 Watt max
Input-Output Response				
Passband Insertion Loss (10 MHz avg)	3300-3600	1.4 dB	1.6 dB max	1.8 dB max
Passband Ripple	3300-3600	0.6 dB	1.0 dB max	1.2 dB max
Passband Return Loss	3300-3600	13 dB	10 dB min	10 dB min
Attenuation:	1-2200	47 dB	40 dB min	40 dB min
	2201-2700	39 dB	35 dB min	35 dB min
	2701-3050	30 dB	25 dB min	25 dB min
	3051-3240	12 dB	10 dB min	10 dB min
	3660-3999	12 dB	10 dB min	10 dB min
	4000-4199	30 dB	25 dB min	25 dB min
	4200-5149	39 dB	35 dB min	35 dB min
	5150-5950	30 dB	25 dB min	25 dB min
	5951-7000	21 dB	16 dB min	16 dB min

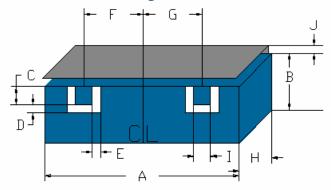
Note: CTS tests each unit to the critical specifications above. Subsequent audits may deviate due to repeatability among different test systems which shall not exceed these allowances. Specification Allowance Insertion Loss 0.1 dB Return Loss 1.0 dB Attenuation 1.0 dB

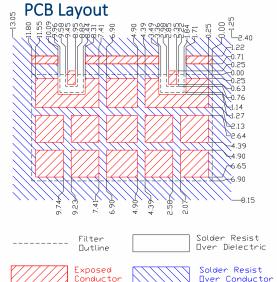
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Mechanical Drawing





Dim.	Nominal (mm)	Tolerance	
Α	8.97	max	
В	5.70	max	
С	0.76	0.13	
D	0.38	0.13	
Е	0.38	0.13	
F	3.30	0.13	
G	3.30	0.13	
Н	3.10	max	
I	0.76	0.13	
J	0.95	0.20	

IMPORTANT: Please assure >=30mils (0.75mm) thickness of dielectric beneath the I/O Pads and the surrounding clearance zone down to the required ground plane.

Please assure sufficient ground vias between the top metal ground plane and the primary ground plane.

Recommended solder: 4-6 mils of SAC305 with reflow including 120s of soak at 217°C, and up to 30 sec peak at 241°C.

NOTE: A width of 9.50mm is necessary to support frequencies as low as 1885MHz for Band 39. If only higher frequency TDD bands are supported, then this smaller space can be allocated on the layout.

Packaging and Marking

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Dimens	ion Unit	s Spec.	Product	Marking			
Reel Diam				CTS 345			
Reel Wei	ght kg	5.5					
Reel Quar	ntity ea.	500	Y	WW			
Customer Feed Direction \rightarrow \rightarrow							
Po MM/(Inches)			Wo MM/(Inches)	Bo MM/(Incl			
MM/(Inches)							
Wo	A _o	Bo	Ko	Po			
0.945 in	0.276 in	0.366 in	0.132 in	0.315 in			
24.0 mm	7.00 mm	9.30 mm	3.35 mm	8.0 mm			

Electrical Response

